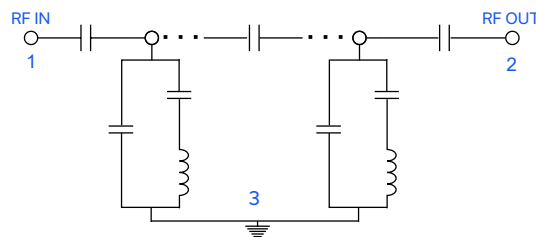


**THE BIG DEAL**

- Pass Band, 26.5 to 58GHz
- Low Insertion Loss, Typ. 1.29dB
- Return Loss, Typ. 15.1dB
- Stop Band Rejection, Typ. 18.7dB
- Power Handling, 1W

*Generic photo used for illustration purposes only***APPLICATIONS**

- Test & Measurement Equipment
- SATCOM
- 5G mmWave Radio Systems

FUNCTIONAL DIAGRAM**PRODUCT OVERVIEW**

Mini-Circuits' HFCN-2652+ is a miniature low-temperature co-fired ceramic (LTCC) high pass filter with a 26.5 to 58GHz passband that supports a variety of applications. This model provides 1.29dB typical insertion loss over a wide band, due to its rugged monolithic construction. Housed in a tiny 1206 ceramic form factor, the filter is ideal for dense signal chain PCB layouts, where it complements MMIC size and performance. The LTCC fabrication process assures minimal RF performance variation while delivering a product that is well-suited for environmental extremes of high humidity and temperature.

KEY FEATURES

Features	Advantages
Ultra-wide Passband	More than an octave bandwidth for wideband applications.
Cost Effective	LTCC is a scalable technology that is cost effective due to ease of production in high quantities.
Small Size 1206	Allows for high layout density of circuit boards, while minimizing effects of parasites.
Surface Mountable	Suitable for very high volume automated assembly process.



CERAMIC

High Pass Filter

HFCN-2652+

50Ω 26.5 to 58 GHz

ELECTRICAL SPECIFICATIONS^{1,2,3} AT +25°C

Parameter		F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Pass Band	Insertion Loss	F4-F5	26.5 - 40	-	0.8	1.5	dB
		F5-F6	40.1 - 51.5	-	1.2	2	
		F6-F7	51.6 - 58	-	2.5	3.6	
	Return Loss	F4-F5	26.5 - 40	-	16.4	-	dB
		F5-F6	40.1 - 51.5	-	15	-	
		F6-F7	51.6 - 58	-	13	-	
Stop Band	Rejection	DC-F1	0.1 - 10.3	-	21.4	-	dB
		F1-F2	10.4 - 20.4	-	16.1	-	
	Freq. Cut-Off ⁴	F3	23.8	-	2.7	-	dB

1. Measured on Mini-Circuits Evaluation Board P/N TB-HFCN-2652C+ with connectors and feedlines effects de-embedded using 2X Thru IEEE P370 method.

2. Bi-directional, RF1 and RF2 ports can be interchanged.

3. This component should not be used as a DC-block. In applications where DC voltage and/or current is present at either the input or output ports, external DC blocking capacitors are required.

4. Typical variation $\pm 3\%$.

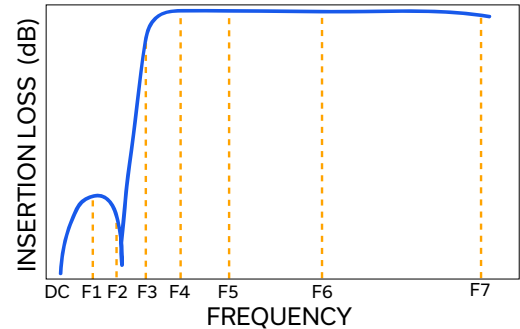
ABSOLUTE MAXIMUM RATINGS⁵

Parameter	Ratings
Operating Temperature	-55°C to +125°C
Storage Temperature	-55°C to +125°C
Input Power ⁶	1W max.

5. Permanent damage may occur if any of these limits are exceeded.

6. Power rating applies only to signals within the passband. Power rating above +25°C operating temperature decreases linearly to 0.5W at +125°C.

TYPICAL FREQUENCY RESPONSE AT +25°C





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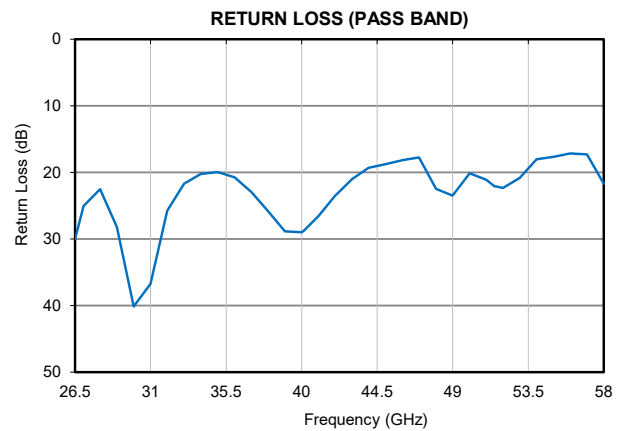
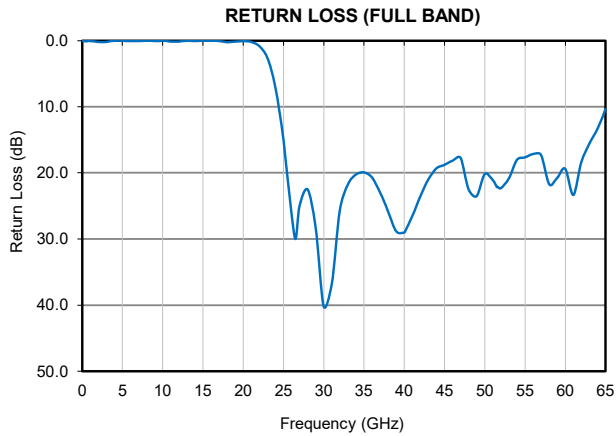
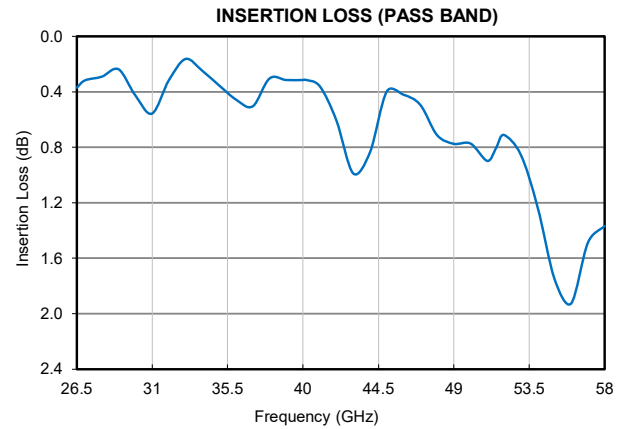
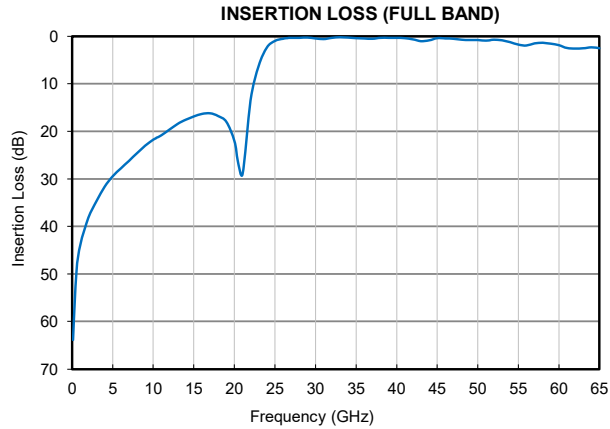
CERAMIC

High Pass Filter

HFCN-2652+

50 Ω 26.5 to 58 GHz

TYPICAL PERFORMANCE GRAPHS AT +25°C





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CERAMIC

High Pass Filter

HFCN-2652+

50Ω 26.5 to 58 GHz

FUNCTIONAL DIAGRAM

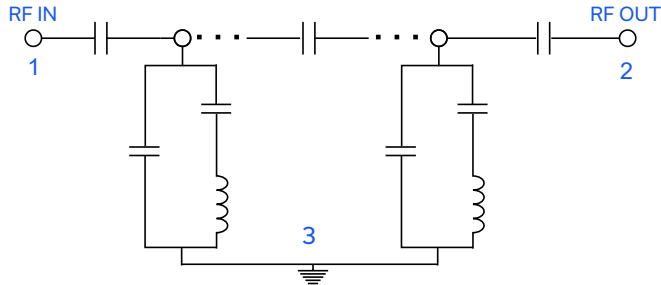
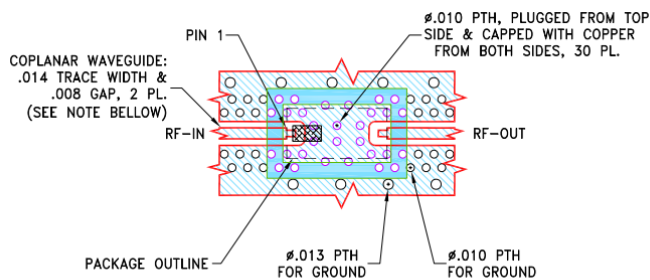


Figure 1. HFCN-2652+ Functional Diagram

PAD DESCRIPTION

Function	Pad Number	Description
RF1 (Note 2)	1	Connects to RF Input Port
RF2 (Note 2)	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-748)

SUGGESTED PCB LAYOUT (PL-748)

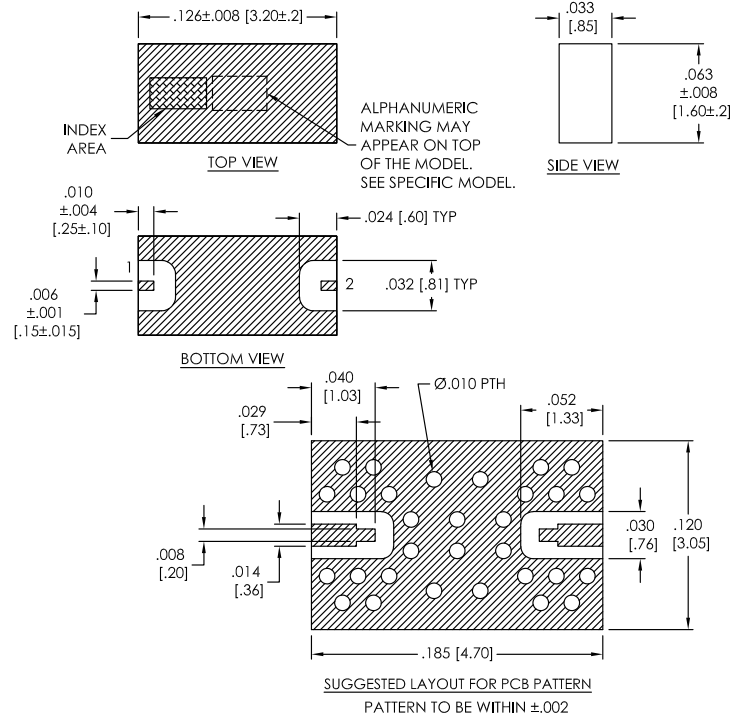


NOTES:

- TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR MEGTRON-7 R5785(N); DIELECTRIC THICKNESS: .0079±.001; COPPER: HVLP/HVLP. FOR OTHER MATERIALS TRACE WIDTH & GAP MAY NEED TO BE MODIFIED.
 - BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
 DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

Figure 2. Suggested PCB Layout PL-748

CASE STYLE DRAWING



Weight: .017 grams.

Dimensions are in inches (mm). Tolerances: 2 Pl.±.01; 3 Pl. ±.005

PRODUCT MARKING*: WE

*Marking may contain other features or characters for internal lot control.



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CERAMIC

High Pass Filter

HFCN-2652+

50Ω 26.5 to 58 GHz

ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASH BOARD.

[CLICK HERE](#)

Performance Data and Graphs	Data Graphs S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	FV1206-12 Finish: Gold over Nickel plating
RoHS Status	Compliant
Tape and Reel	TR-F75
Suggested Layout for PCB Design	PL-748
Evaluation Board	TB-HFCN-2652C+ Gerber File
Environmental Rating	ENV06T10

NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html



Ceramic Highpass Filter

HFCN-2652+

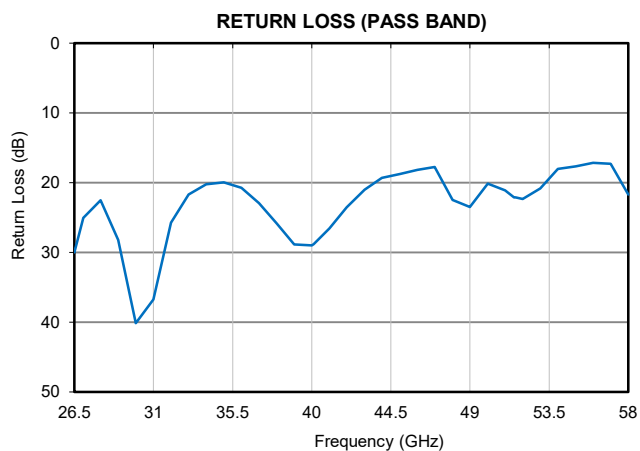
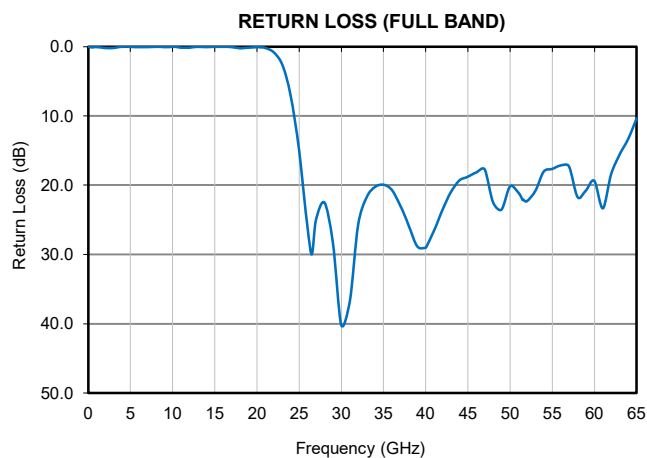
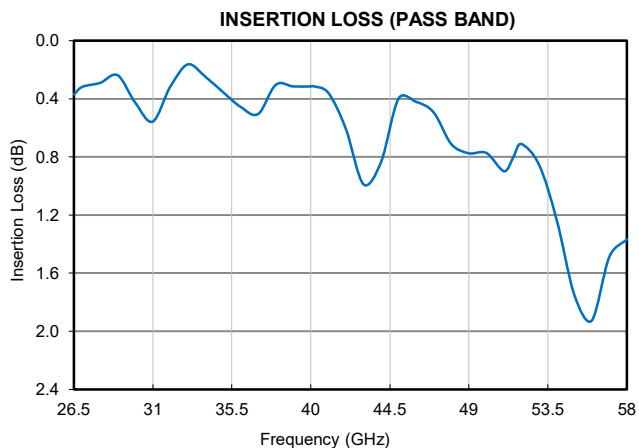
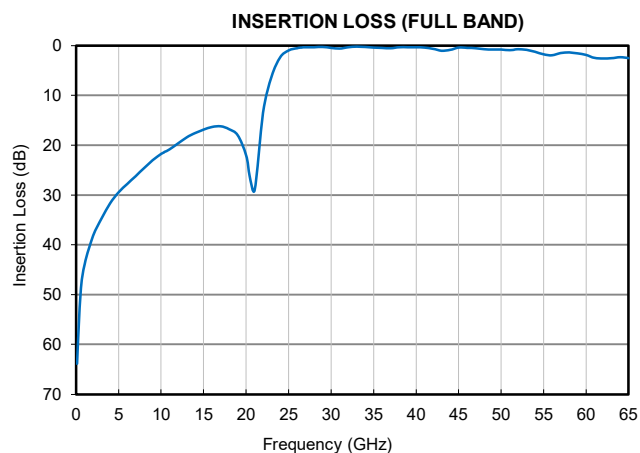
Typical Performance Data

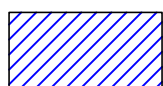
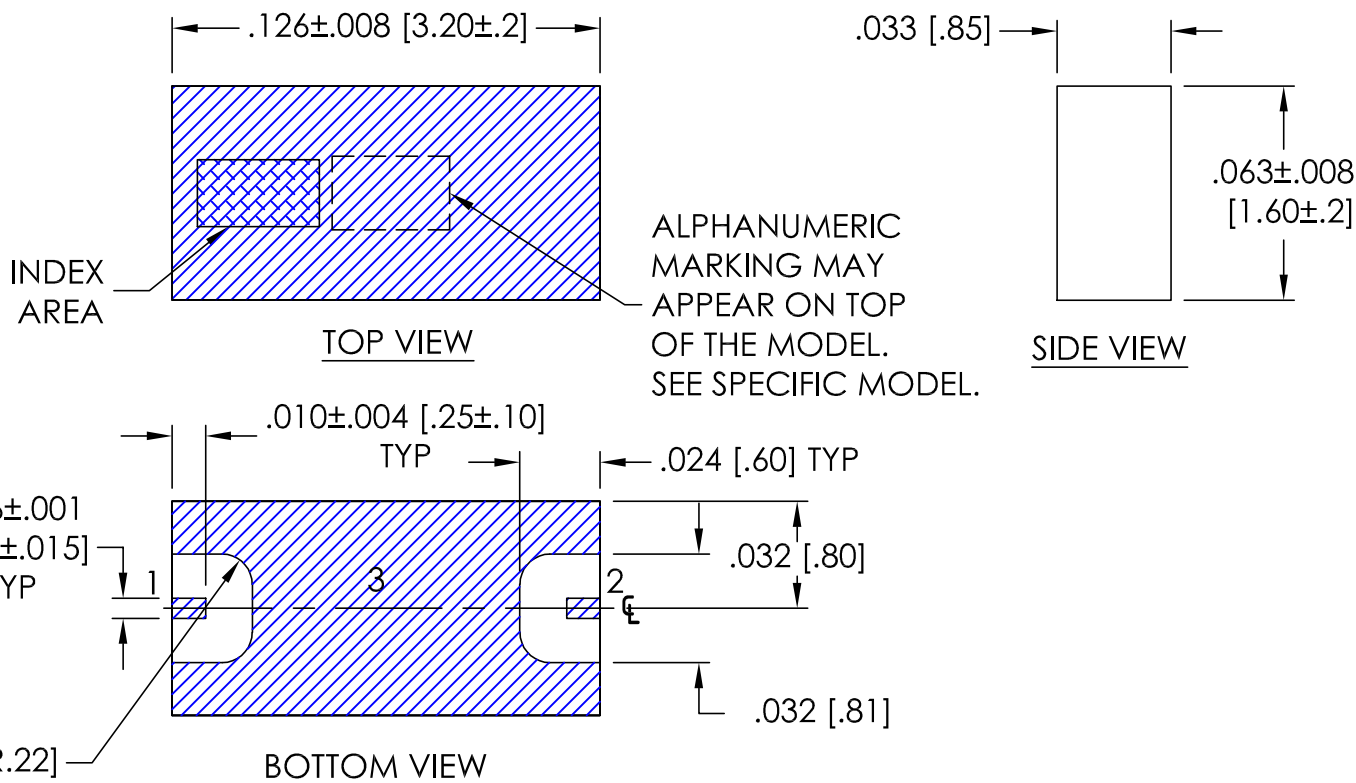
FREQUENCY (GHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
0.1	63.87	0.06
0.5	49.70	0.11
1.0	43.78	0.05
2.0	38.18	0.20
3.0	34.63	0.19
4.0	31.64	0.01
5.0	29.40	0.04
6.0	27.76	0.07
7.0	26.18	0.06
8.0	24.54	0.01
9.0	23.01	0.05
10.0	21.73	0.04
10.3	21.43	0.00
10.4	21.34	0.02
11.0	20.78	0.14
12.0	19.62	0.14
13.0	18.41	0.01
14.0	17.53	0.06
15.0	16.85	0.02
16.0	16.30	0.03
17.0	16.19	0.06
18.0	16.77	0.23
19.0	17.96	0.14
20.0	21.99	0.08
20.4	26.08	0.09
21.0	28.95	0.18
22.0	13.51	0.84
23.0	6.15	2.59
24.0	2.32	7.06
25.0	0.96	15.06
26.0	0.50	26.12
26.5	0.37	30.01
27.0	0.32	25.03
28.0	0.29	22.52
29.0	0.24	28.23
30.0	0.43	40.17
31.0	0.56	36.79
32.0	0.32	25.77
33.0	0.16	21.71
34.0	0.25	20.24
35.0	0.35	19.94
36.0	0.46	20.73
37.0	0.50	22.95
38.0	0.30	25.83
39.0	0.31	28.85
40.0	0.31	29.01
40.1	0.31	28.82
41.0	0.36	26.57
42.0	0.61	23.54
43.0	0.99	20.99
44.0	0.83	19.32
45.0	0.40	18.79
46.0	0.42	18.15
47.0	0.49	17.77
48.0	0.71	22.51
49.0	0.77	23.51
50.0	0.77	20.17
51.0	0.90	21.10
51.5	0.81	22.12
51.6	0.78	22.10
52.0	0.71	22.32
53.0	0.85	20.81
54.0	1.23	18.04
55.0	1.74	17.67
56.0	1.93	17.13
57.0	1.49	17.31
58.0	1.37	21.71
59.0	1.55	20.75
60.0	1.85	19.39
61.0	2.46	23.33
62.0	2.55	18.35
63.0	2.51	15.57
64.0	2.33	13.33
65.0	2.48	10.38

Ceramic Highpass Filter

HFCN-2652+

Typical Performance Data





METALLIZATION

Weight: .017 grams.

Dimensions are in inches (mm). Tolerances: 2 Pl. $\pm .01$; 3 Pl. $\pm .005$

Notes:

1. Case material: Ceramic.
2. Termination Finish: **as shown below or indicated on Data Sheet.**
For RoHS Case Styles: Gold plate over Nickel plate All models, (+) suffix.

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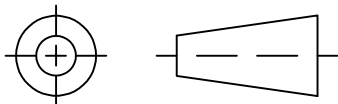
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

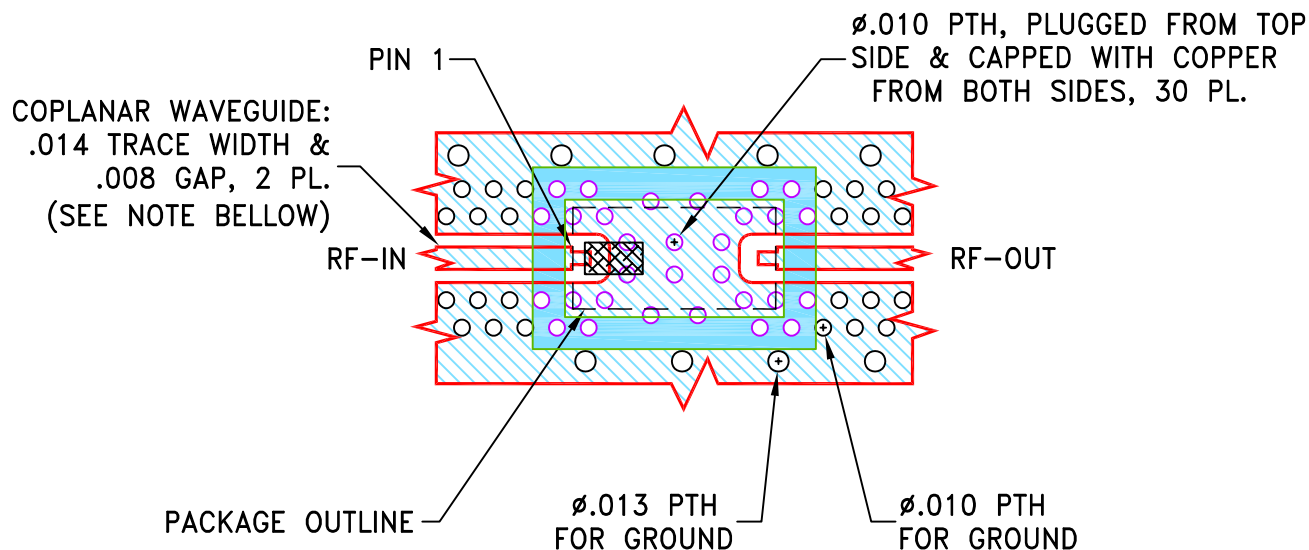
RF/IF MICROWAVE COMPONENTS

THIRD ANGLE PROJECTION



REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	EC0-016075	NEW RELEASE	12/09/22	ITG	IL

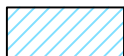
SUGGESTED MOUNTING CONFIGURATIONFV1206-12 CASE STYLE

NOTES:

- TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR MEGTRON-7 R5785(N); DIELECTRIC THICKNESS: .0079±.001; COPPER: HVLP/HVLP. FOR OTHER MATERIALS TRACE WIDTH & GAP MAY NEED TO BE MODIFIED.
- BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED	INITIALS		DATE
DIMENSIONS ARE IN INCHES	DRAWN	ITG	12/09/22
TOLERANCES ON:	CHECKED	GF	12/09/22
2 PL DECIMALS ±	APPROVED	IL	12/09/22
3 PL DECIMALS ± .005			
ANGLES ±			
FRACTIONS ±			

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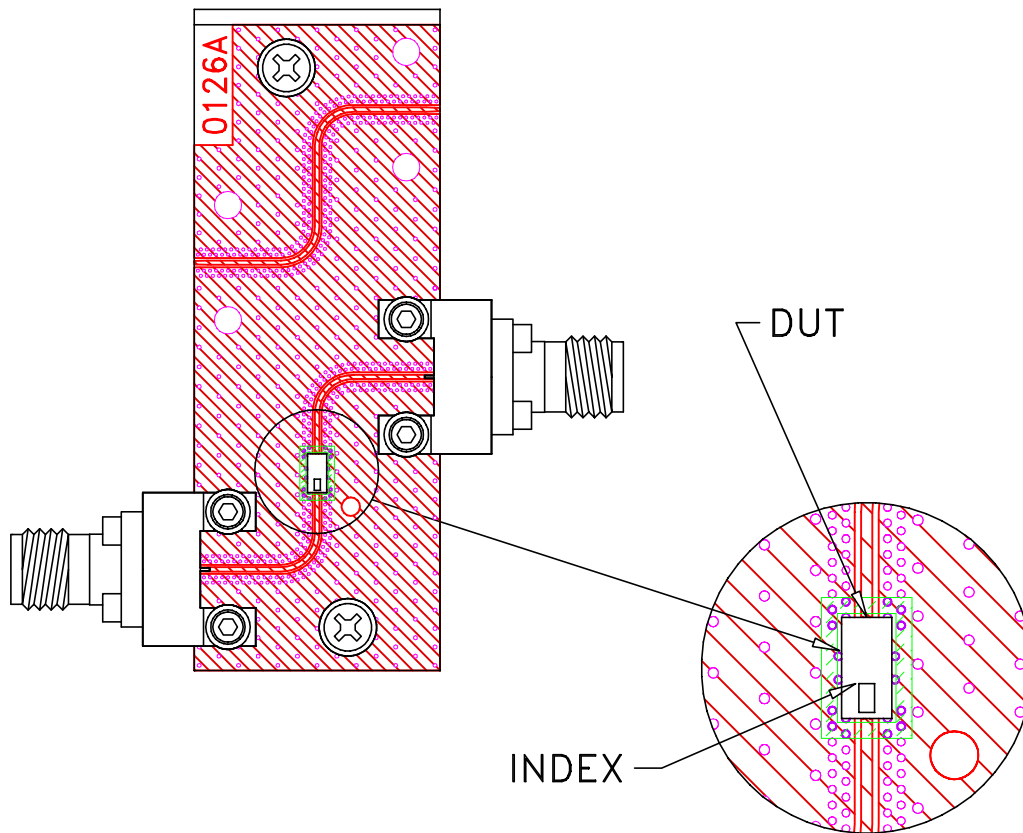
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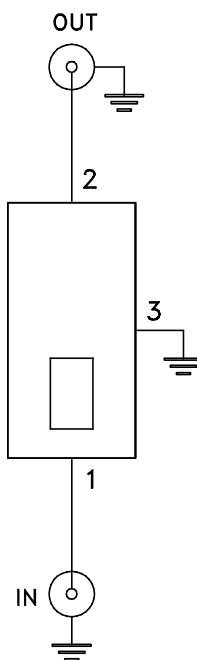
PL, FV1206-12, TB-HFCN-2502+

SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-748	OR
FILE:	98PL748	SCALE: 8:1	SHEET: 1 OF 1

Evaluation Board and Circuit



TB-HFCN-2652C+



Schematic Diagram

1. 50 Ohm 1.85 End Launch Female connectors.
2. PCB Material: Megtron 7 R5785(N) or equivalent, Dielectric Constant=3.4, Thickness=.0079 inch.

 **Mini-Circuits®**



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Solder Reflow Heat	Sn-Pb Eutectic Process 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020C, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, Test B,B1, 95% Coverage
Thermal Shock	-55° to +125°C, 15 min dwell,250 cycles	MIL-STD-202, Method 107
Bend Test	1mm, deflection for 5 seconds Span of bending: 2.75"	--
High Temp Storage	125°C to 1000 Hrs	---